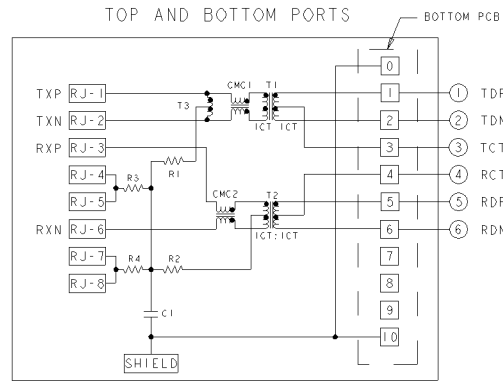
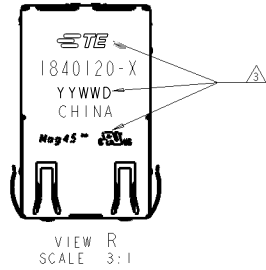


REV	DATE	REVISIONS	DATE	BY	APPD
AA	00				
A		NEW RELEASE		SANC2005	CS PD
B		ECO-08-022964		SANC2006	KD KL
C		ECO-11-019412		20080011	PP LJ

### S814 MAGNETIC CIRCUIT STACKED



C1 = 1000pF, 24V, ±10%, X7R DECOUPLING CAP.  
 R1-R4 = 75 OHMS, 1/16 W, ±5% RESISTORS

△ MATERIALS:  
 PLASTIC HOUSING: BLACK, THERMOPLASTIC FLAMMABILITY RATING UL 94V-0  
 SHIELD: BRASS, PLATED WITH 0.76 μm SEMI-BRIGHT NICKEL, POST DIPPED WITH 2.54 μm MIN SAC SOLDER ON SOLDER TAILS  
 CONTACTS: PHOSPHOR BRONZE, 1.27 μm MIN OVERALL NICKEL UNDER PLATE WITH SELECT 1.27 μm MIN GOLD AT MATING INTERFACE AND 2.54 μm MIN MATTE TIN ON SOLDER TAILS.  
 LED: DIFFUSED EPOXY LENS, CARBON STEEL LEAD FRAME  
 LEADS: PREPLATED WITH 2.03 μm MIN SILVER OVER 1.02 μm MIN NICKEL UNDERPLATE OVER 1.02 μm MIN COPPER UNDERPLATE. POST-PLATED WITH 2.54 μm MIN MATTE TIN AND/OR SAC SOLDER DIP OR PURE TIN SOLDER DIP  
 INTERNAL MAGNETICS PC BOARD: HIGH TEMP PCB, TG > 170°C

△ MAGNETICS  
 APPLICATION: 10/100 BASE-T  
 IMPEDANCE: 100 OHMS  
 TURNS RATIO (CHIP: CABLE): TX = 1:1, RX = 1:1  
 OPEN CIRCUIT INDUCTANCE (OCL): 350 μH MIN @ 100kHz, 0.1VRMS, 8mADC BIAS FROM 0°C TO 70°C, TX AND RX  
 PERFORMANCE @ 25°C:  
 INSERTION LOSS (IL): 1.1dB MAX FROM 0.5MHz TO 100MHz  
 RETURN LOSS (RL): 18dB MIN FROM 0.5MHz TO 30MHz  
 18-20LOG(f/30)dB MIN FROM 30.1MHz TO 60MHz  
 12dB MIN FROM 60.1MHz TO 80MHz  
 CROSSTALK ATTENUATION: 35dB MIN FROM 0.5MHz TO 40MHz  
 33-20LOG(f/50)dB MIN FROM 40.1MHz TO 100MHz  
 COMMON MODE REJECTION RATIO (CMRR): 30dB MIN FROM 0.5MHz TO 100MHz  
 ISOLATION VOLTAGE: COMPLIES WITH IEEE802.3 2002, PARA 23.5.1.1, ITEM b.

△ TE CONNECTIVITY LOGO, PART NUMBER, DATE CODE, COUNTRY OF ORIGIN, AGENCY APPROVAL MARKING LOGO LOCATED IN THE APPROXIMATE AREA SHOWN. DATE CODE YY IS YEAR, WW IS WORK WEEK, D IS DAY OF WEEK, WITH SUNDAY=1

4. OPERATING TEMPERATURE: FROM 0° C TO + 70° C.

△ RJ45 CAVITY CONFORMS TO FCC RULES AND REGULATION PART 68 SUBPART F.

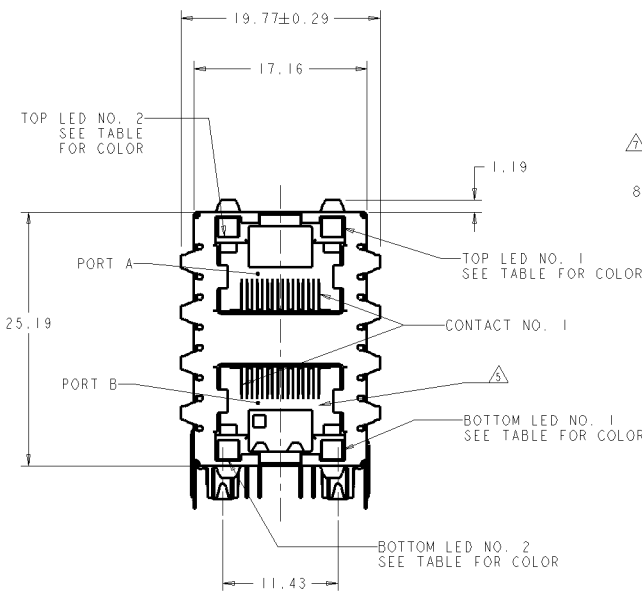
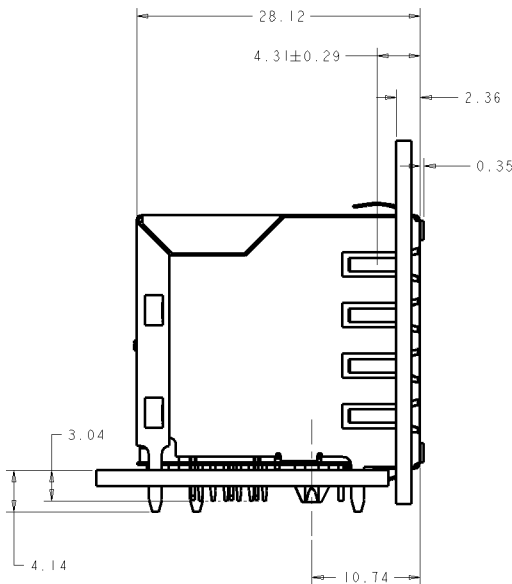
6. LED'S COMPLIANT WITH IEC60825-1 SAFETY OF LASER PRODUCTS WHEN OPERATED AT CURRENT OF 20 mA MAX. LED IS DRIVEN WITH CONSTANT CURRENT AT APPROX 20mA. LED COLOR:

DOMINANT WAVELENGTH (λD): GREEN 568 nm TYP @ IF=20mA  
 FORWARD VOLTAGE (VF): GREEN 2.2V TYP @ IF=20mA

DOMINANT WAVELENGTH (λD): YELLOW 588 nm TYP @ IF=20mA  
 FORWARD VOLTAGE (VF): YELLOW 2.1V TYP @ IF=20mA

△ INDICATED CONNECTIONS ARE FOR NIC CONFIGURATION. THE MAGNETICS ARE ASYMMETRICAL AND DO NOT SUPPORT AUTO-MDI/MDIX.

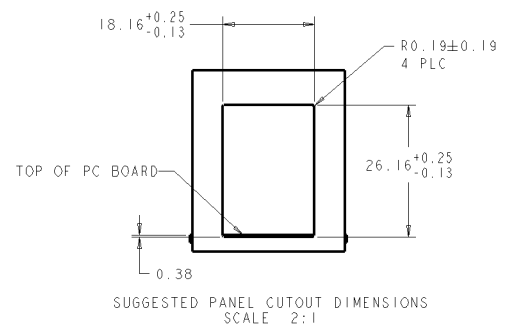
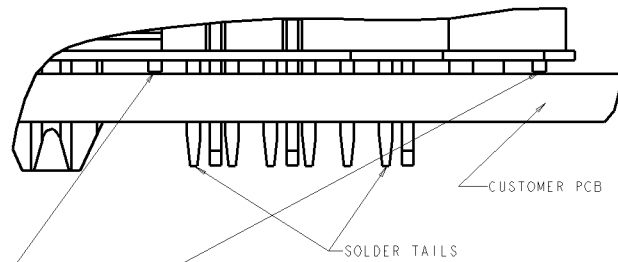
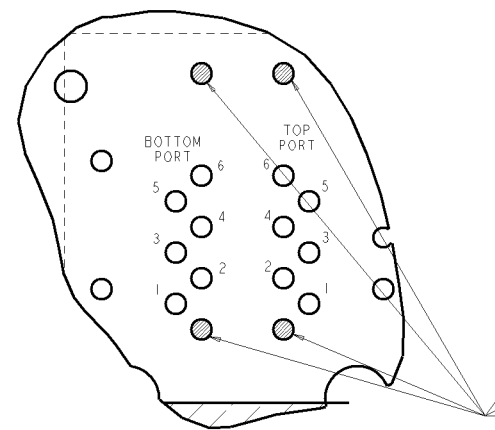
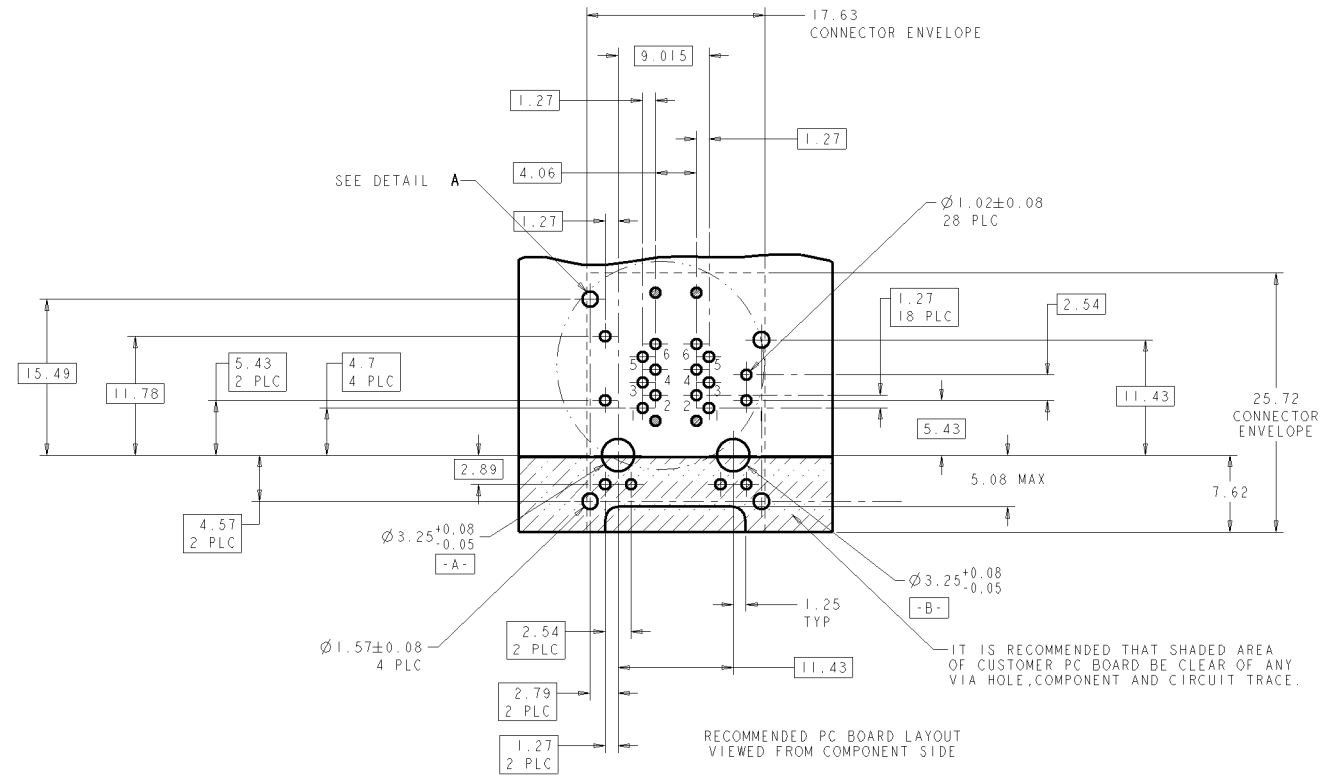
8. THESE PARTS ARE RECOMMENDED FOR WAVE SOLDERING PROCESS. PEAK SOLDERING TEMPERATURE IS 260 °C MAX, 10 SECONDS MAX.



GRN/YEL	GRN/YEL	GRN/YEL	GRN/YEL	1840120-4
GREEN	YELLOW	GREEN	YELLOW	1840120-3
YELLOW	GREEN	GREEN	YELLOW	1840120-2
GREEN	GREEN	GREEN	GREEN	1840120-1
BOTTOM LED NO. 2	BOTTOM LED NO. 1	TOP LED NO. 2	TOP LED NO. 1	PART NO.

THIS DRAWING IS A CONTROLLED DOCUMENT		DESIGNED BY: G. GILLETTE	SOURCE CODES: S814
DRAWN BY: J. B. AMATO		DATE: 03 JAN 2006	
CHECKED BY: J. B. AMATO		DATE: 03 JAN 2006	
APPROVED BY: J. B. AMATO		DATE: 03 JAN 2006	
DIMENSIONS: (mm) (INCHES)		PRODUCT SPEC: 108-2100	APPLICATION SPEC: -
MATERIAL: -		REVISION: -	DATE: 00779
CUSTOMER DRAWING		DATE: 00779	REV: 1

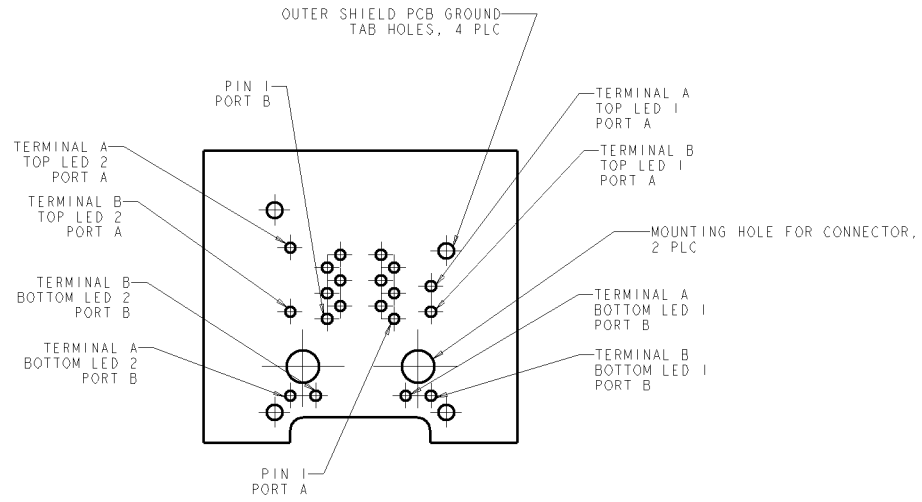
REV	DATE	DESCRIPTION	BY	CHKD
AA	00	SEE SHEET 1		



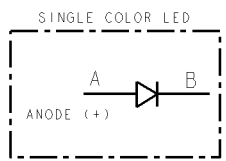
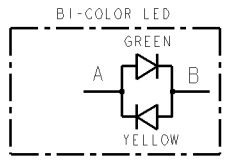
PIN #0 & PIN #10 ON MOD JACK ARE STUB PINS WITH LENGTH SIMILAR TO PCB STANDOFF HEIGHT. PRECAUTIONS SHOULD BE TAKEN IN PCB DESIGN TO GUARD AGAINST SHORTING TRACES TO STUB PINS.

THIS DRAWING IS A CONTROLLED DOCUMENT		DESIGNED BY: G. GILLETTE CHECKED BY: D. AMATO DATE: 03 JAN 2006	REVISED BY: S. B. COLLINGS DATE: 03 JAN 2006	DRAWN BY: J. FLICKINGER DATE: 03 JAN 2006	PRODUCT SPEC: 108-2100 APPLICATION SPEC:	SIZE: CASE CODE: DRAWING NO: A   00779 ©=1840120 SHEETS: 2 OF 3	
DIMENSIONS: (mm) (INCHES) DIMENSIONS: (mm) (INCHES)	DIMENSIONS: (mm) (INCHES) DIMENSIONS: (mm) (INCHES)	DIMENSIONS: (mm) (INCHES) DIMENSIONS: (mm) (INCHES)	DIMENSIONS: (mm) (INCHES) DIMENSIONS: (mm) (INCHES)	DIMENSIONS: (mm) (INCHES) DIMENSIONS: (mm) (INCHES)	DIMENSIONS: (mm) (INCHES) DIMENSIONS: (mm) (INCHES)	DIMENSIONS: (mm) (INCHES) DIMENSIONS: (mm) (INCHES)	
MATERIAL: 1		MATERIAL: 1		MATERIAL: 1		MATERIAL: 1	
CUSTOMER DRAWING		CUSTOMER DRAWING		CUSTOMER DRAWING		CUSTOMER DRAWING	

REV	DATE	DESCRIPTION	DATE	BY	APP
AA	00				
		SEE SHEET 1			



LED HOLE DESIGNATIONS VIEWED FROM COMPONENT SIDE  
 SCALE 4:1



THIS DRAWING IS A CONTROLLED DOCUMENT		DESIGNED BY: G. GILLETTE DATE: 03 JAN 2006 CHECKED BY: P. D'AMATO DATE: 03 JAN 2006 DRAWN BY: P. FLICKINGER	INTEGRATED MAGNETIC STACKED MODULAR JACK, 2X1 W/LEDS, 10/100 ETHERNET, RJ45, GROUND SHIELD, HT PCB
DIMENSIONS: mm (INCHES) DIMENSIONS: mm (INCHES)	DIMENSIONS: mm (INCHES) DIMENSIONS: mm (INCHES)	PRODUCT SPEC: 108-2100 APPLICATION SPEC:	SIZE: CASE CODE: DRAWING NO: 40 REV: A   00779 © 1840120 SHEETS: 3 OF 3 REV: C
MATERIAL: UNLESS OTHERWISE SPECIFIED		CUSTOMER DRAWING	DATE: N/A